

# ***SOLDERING ALUMINUM, A NEW LOOK***



# *AUTHORS*



Alan E. Gickler and F. Larry LePrevost

Johnson Manufacturing Company

Princeton, Iowa

Tsung Yu Pan and Armando M. Joaquin

Ford Motor Company, Ford Research Laboratory

Dearborn, Michigan

Craig A. Blue and Mike L. Santella

Oak Ridge National Laboratory, Metals and Ceramics Division

Oak Ridge, Tennessee

# OUTLINE



- Introductions by Alan Gickler
  - why solder aluminum
  - what processes are available
  - what materials are used
  - details
- Manufacturing process by F. Larry LePrevost
  - heating method discussion
  - materials and methods
  - results
  - conclusion

# *GENERAL DISCUSSION*



- Why solder aluminum
  - less distortion vs. other fusion joining
  - low capital investment
  - ease of assembly
  - low production costs
  - repairable

# *TYPICAL APPLICATIONS*



- Heat exchangers
  - Electronic or electrical capacitors
  - Light bulbs
- note:
- **none of these applications require high strength, but they do demand NO galvanic corrosion over time**

# *WHAT PROCESSES ARE AVAILABLE*



- Fluxless
  - mechanical rubbing
  - ultrasonic bath
  - thermal spray
- With flux
  - induction
  - flame
  - infrared
  - hotplate
  - furnace
  - soldering iron
  - laser
  - arc lamp

# *WHAT MAKES IT DIFFICULT*

- Oxide layer
  - remove by mechanical means
  - remove by flux
    - organic amine - up to 285°C
    - chloride or fluoride - up to 400°C
    - fluoroaluminate - above 550°C
- Additions to aluminum
  - magnesium
  - vanadium and chromium
- Difficulty of heating the joint
- Flux interferes with alloy wetting

# SOLDERS

- Tin/Zinc- soft solder
  - 92Sn/8Zn (eutectic)
  - 91Sn/9Zn, 80Sn/20Zn, 75Sn/25Zn, 70Sn/30Zn, 60Sn/40Zn
  - in literature
    - 90Sn/9.1Zn/0.6Al (eutectic), 76Sn/21Zn/3Al, 71.5Sn/25Zn/3.5Al, 67Sn/27Zn/3Al
    - 55Sn/33Zn/11Al/1Cu, 67Sn/17Zn/15Al/1Cu
- Zinc/Aluminum- hard solder
  - 98Zn/2Al
  - 97Zn/3Al, 95Zn/5Al (eutectic ?), 90Zn/10Al, 85Zn/15Al, 80Zn/20Al
- Tin/lead or cadmium bearing
  - **NOT RECOMMENDED**



# *DETAILS*

- Pre plate aluminum with nickel or zinc
- Solder to steel, copper, brass, stainless, ...
  - different thermal expansion during and after soldering
  - how to heat both to correct soldering temperature
  - what flux to use
  - galvanic corrosion issues
- Heat the component not the solder
  - may involve heating the entire component to near soldering temperature and then applying local heat to the joint-
  - flux may expire before components are at soldering temperature- time is of the essence
- Remove flux residue after soldering
  - may still be reactive
  - can cause contamination of surrounding area
  - visual
- What is possible in lab may be difficult in production

*IT'S ALWAYS THIS  
COMPLICATED*



# *NOTED CONTRIBUTORS:*



Ford AMTD - Plasma

Ford Norwood - Thermal Spray

Robotron - Induction

Rofin-Sinar - Laser

ORNL / Vortek - Plasma IR Lamp

# *MOTHER NATURE'S REQUIREMENTS*



- Best understood by observation, reason and experiment
- Experiments tests our knowledge, so allow sufficient time for trial & error
- Forces at work: chemical, electrical, mechanical, physical, thermodynamic, gravity and optics (all overlapping)

# *FROM A CHEMICAL VIEWPOINT*



- Type of product and its end use
- Susceptibility to galvanic corrosion
- Using flux, or swaging (fluxless) method of soldering
- Complete removal of flux residue

# *THE PHYSICAL PROSPECTIVE*



- Alloy of aluminum parts being joined
- How were parts formed, stresses
- Thickness of materials to be soldered
- Joint design and strength requirement
- Does shape permit uniform heating

# *THERMODYNAMIC FACTORS*



- What type(s) of heat are best suited for production environment
- Adequate VOLUME of heat must be supplied to all parts simultaneously
- Control of heating and cooling rates to minimize, re alloying and warping

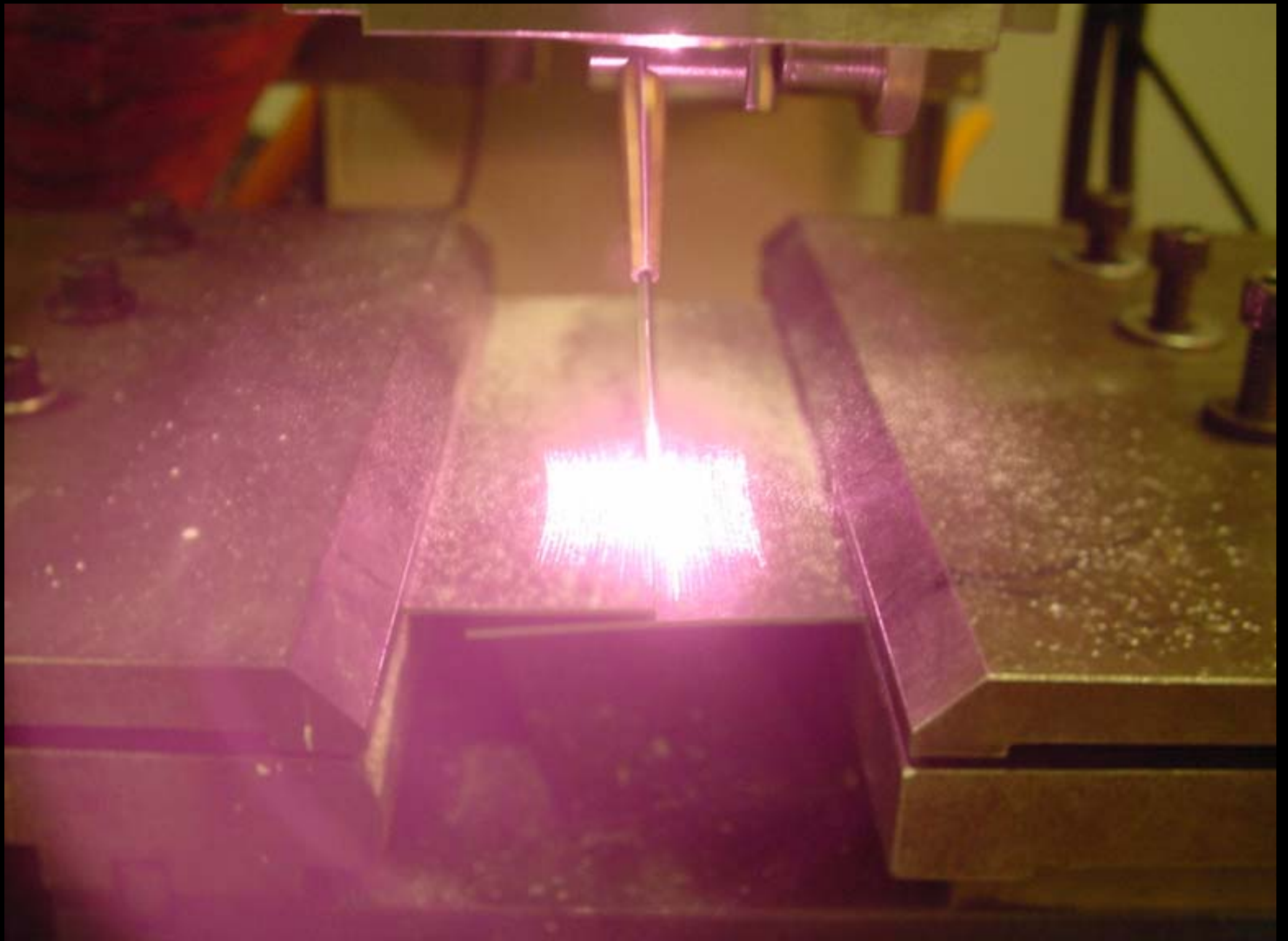




# *HEATING METHODS*



- Hot plate, Iron, open-flame, torch
- Oven, vacuum, atmosphere, air
- Heat by induction
- Diode or YAG laser
- Plasma IR lamp
- Plasma arc spray



# *OVER HEATING*



- Too much time / temperature
- Warping of light gage materials
- Stress relieving, annealing
- Hot cracking
- Re-alloying of parent material
- Dreaded melt down

# *HYBRID HEATING*



- Volume of primary heat, to prevent loss
- Specific or localized heat, brings parts and filler metal to soldering temperature in a controlled fashion

# *HOT PLATE & TORCH COMBO*

- Combining the generalized heat of a hot plate with specific heat from a torch is usually very effective in the laboratory.



# *PLASMA IR, BEST OF SHOW!*

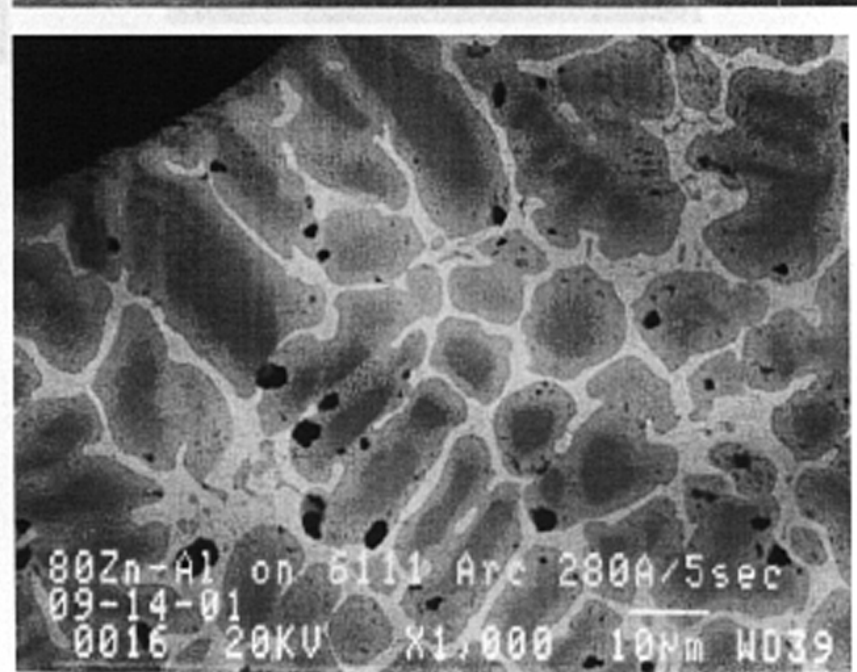
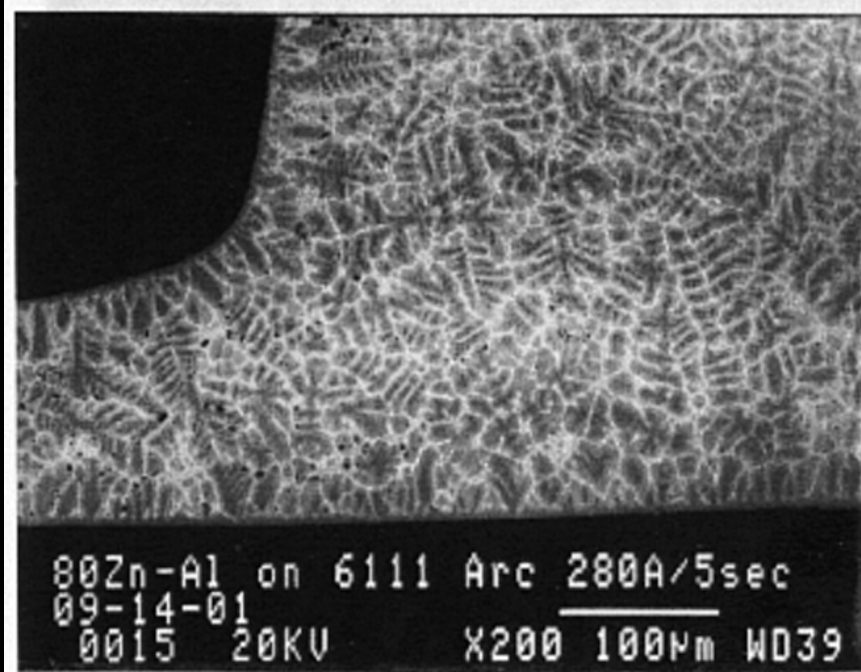
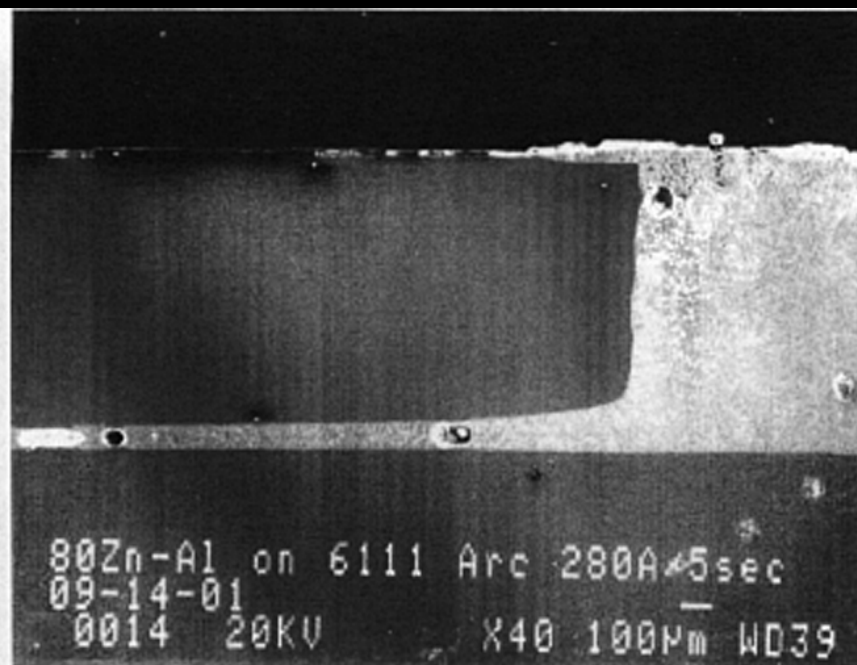


- High density infrared heat source demonstrated successful results with 80Zn/20Al at 490°C
- Joint is stronger than parent material
- Minimum annealing, softening of metal
- No hot cracks in tests with IR heat

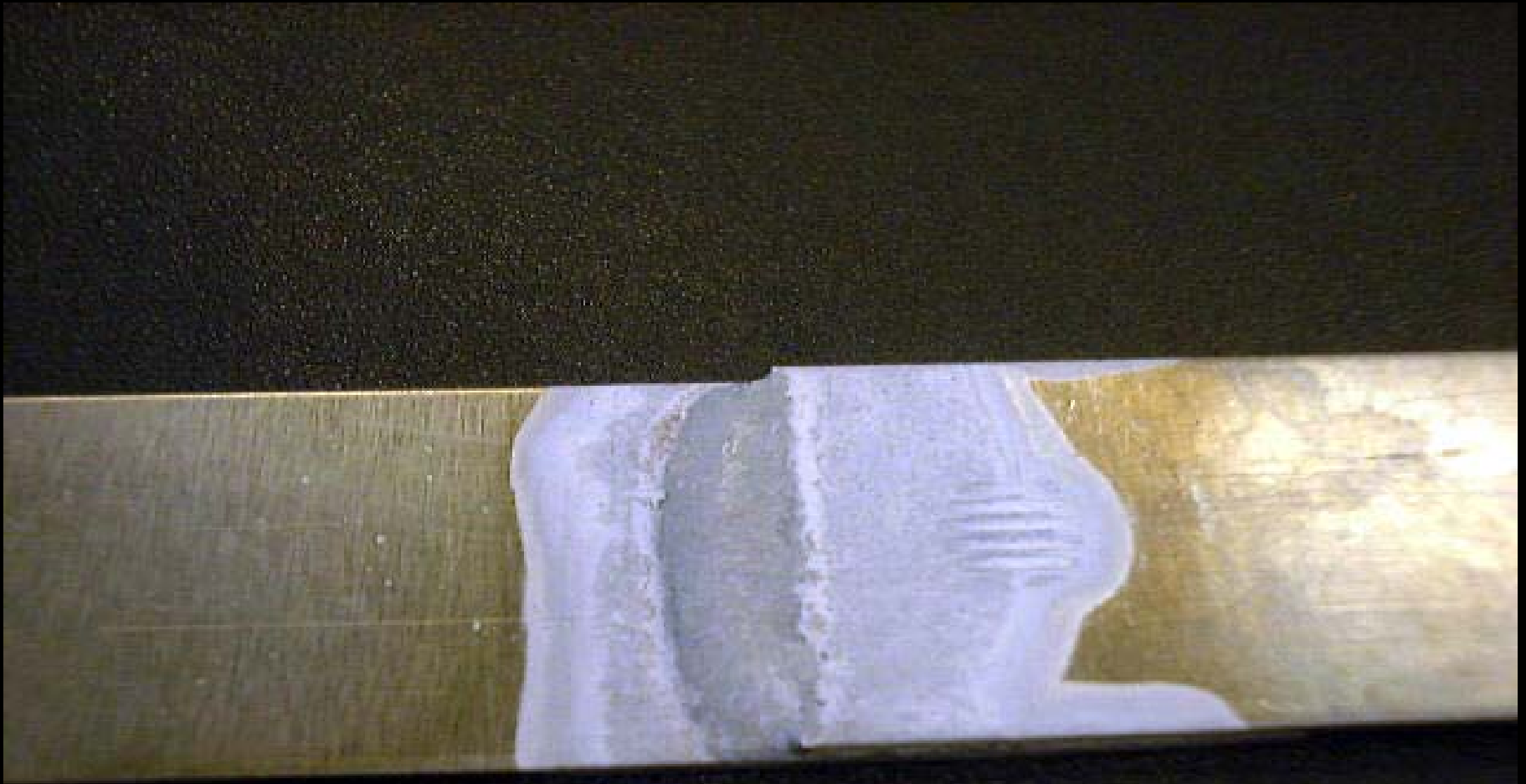
# *PLASMA ARC LAMP HARD SOLDER*



- Good penetration of Zn/Al through underside of joint
- Very few voids found in joint
- Dendritic structure of solidified Zn/Al
- Aluminum rich precipitates in Zn-Rich matrix

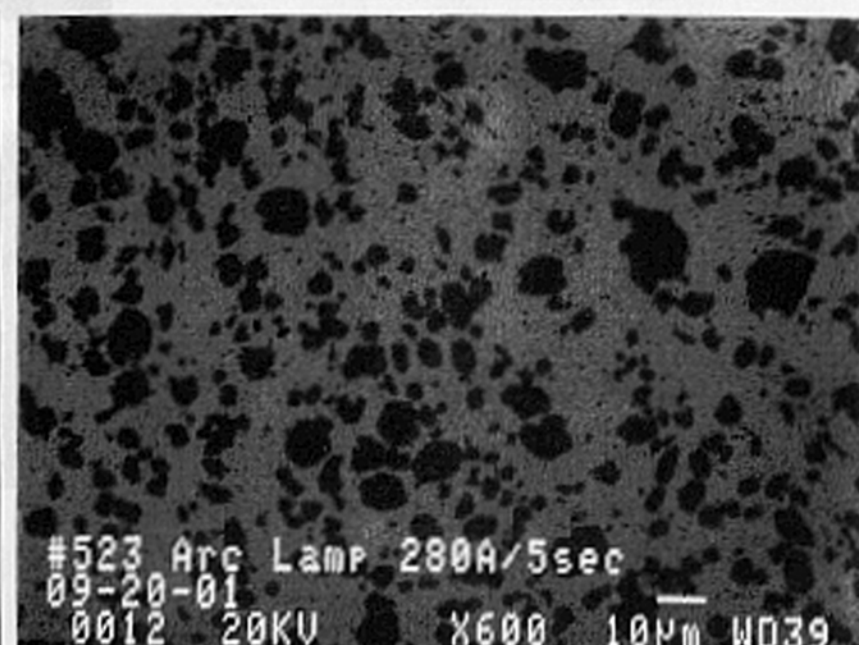
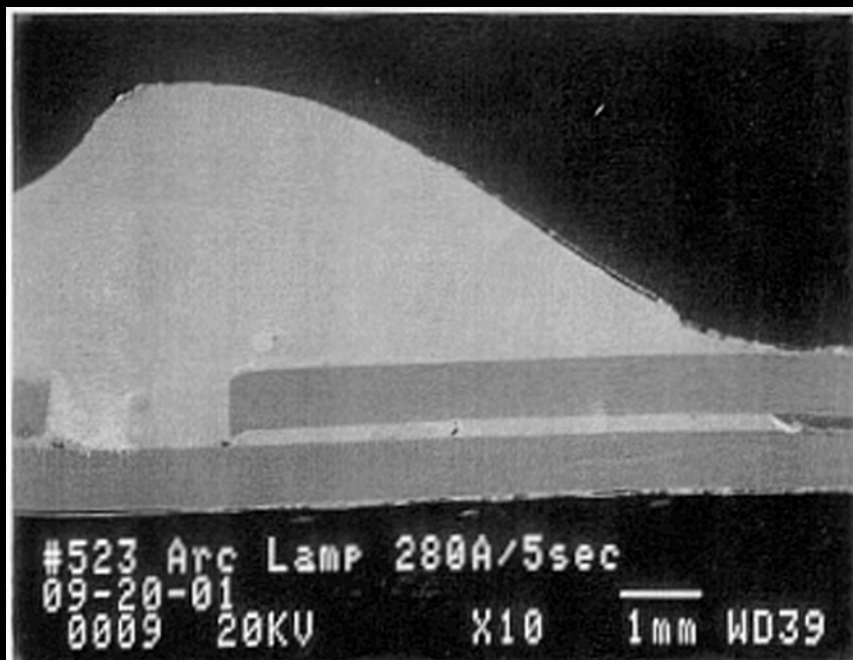






# *PLASMA ARC LAMP BODY SOLDER*

- Good flow of solder into overlapped joint region
- Good viscous “bump” of solder above joint for seam filling
- $\text{Cu}_6\text{Sn}_5$  intermetallics in Sn matrix in solder (typical)
- Almost no separate layer near interface with Zn/Cu in Sn matrix





JOHNSON'S #523 LEAD-FREE  
SEMI SOLID BODY SOLDER  
ALLOY 82Sn/15Cu/3Zn,  
MELTING TEMPERATURE  
428 - 940 F as determined by  
DTA at Ford Research Lab  
USED BY FORD AND OTHER  
AUTO ASSEMBLY PLANTS

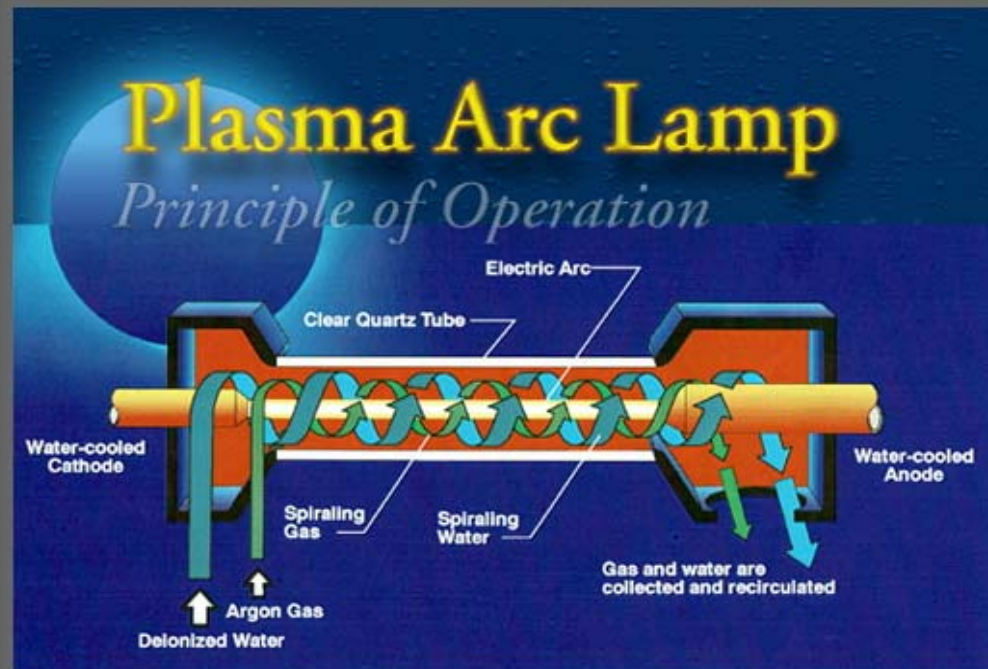
#524 EXPERIMENTAL  
SEMI SOLID BODY SOLDER  
ALLOY 85Sn/12.5Cu/2.5Zn,  
NARROWER MELTING RANGE  
Estimated 428 -880 F  
EXHIBITED MOST SLUMP OF  
THE SOLDERS TESTED

#527 FORD BODY SOLDER  
ALLOY 80.3Sn/16.7Cu/3Zn,  
WIDER MELTING RANGE  
Estimated 428 - 980 F  
USED BY FORD DEARBORN  
EXHIBITED LEAST AMOUNT  
OF SLUMP OF SOLDERS  
TESTED

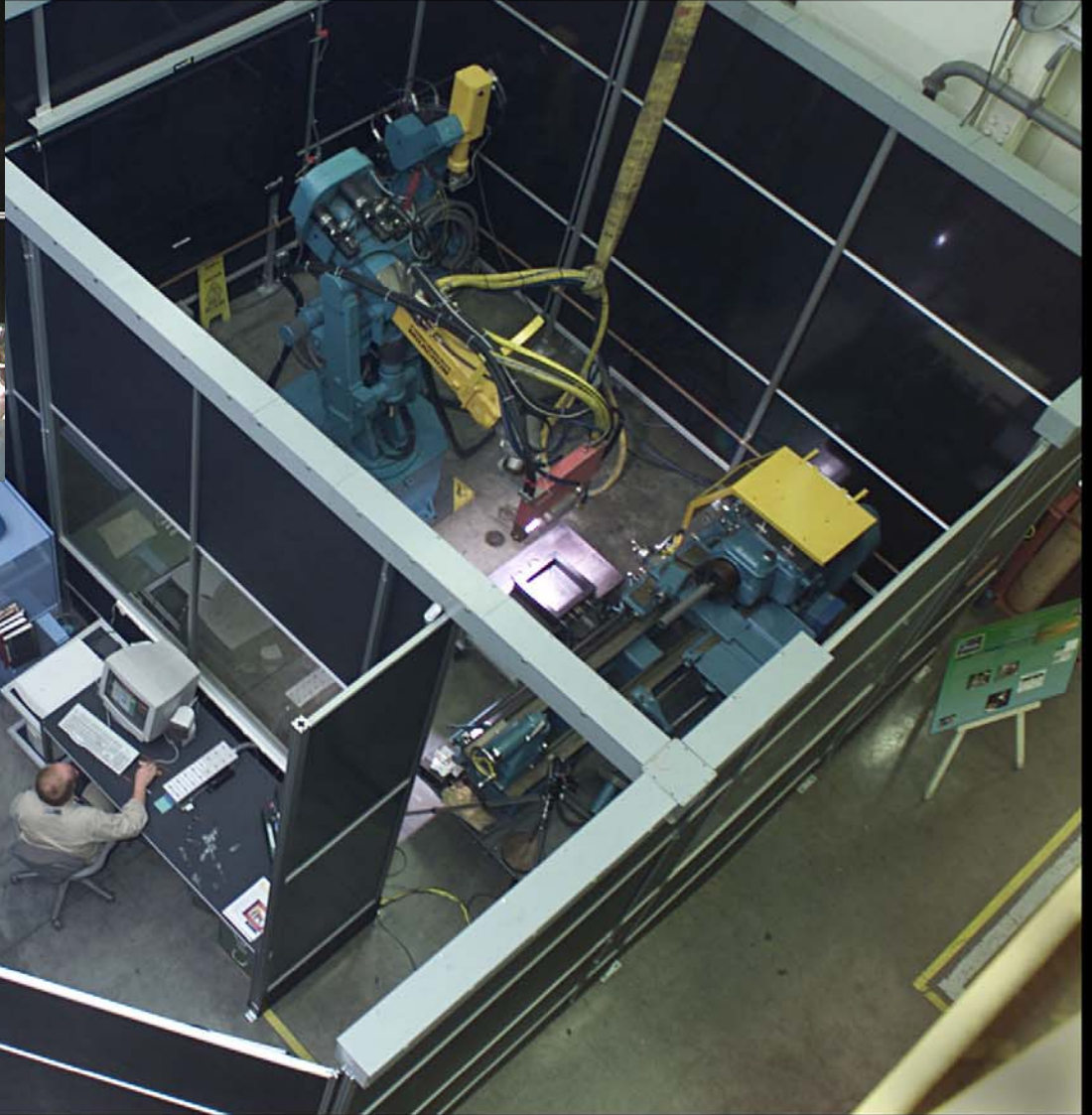
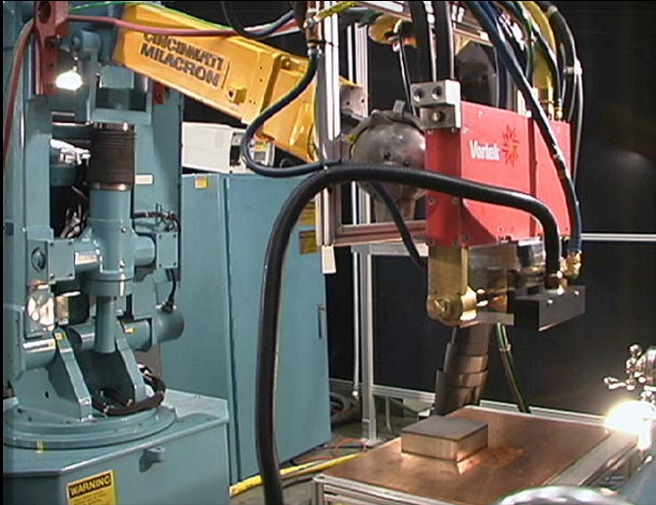
---

F. Larry LePrevost  
Johnson Mfg. Co.  
Princeton, Iowa 52768  
Tel 800-747-0030  
Fax 563-289-3825

# PLASMA ARC LAMP OPERATION



# PLASMA ARC LAMP FACILITY



C0000653-05

# *PLASMA RADIANT SOURCE*

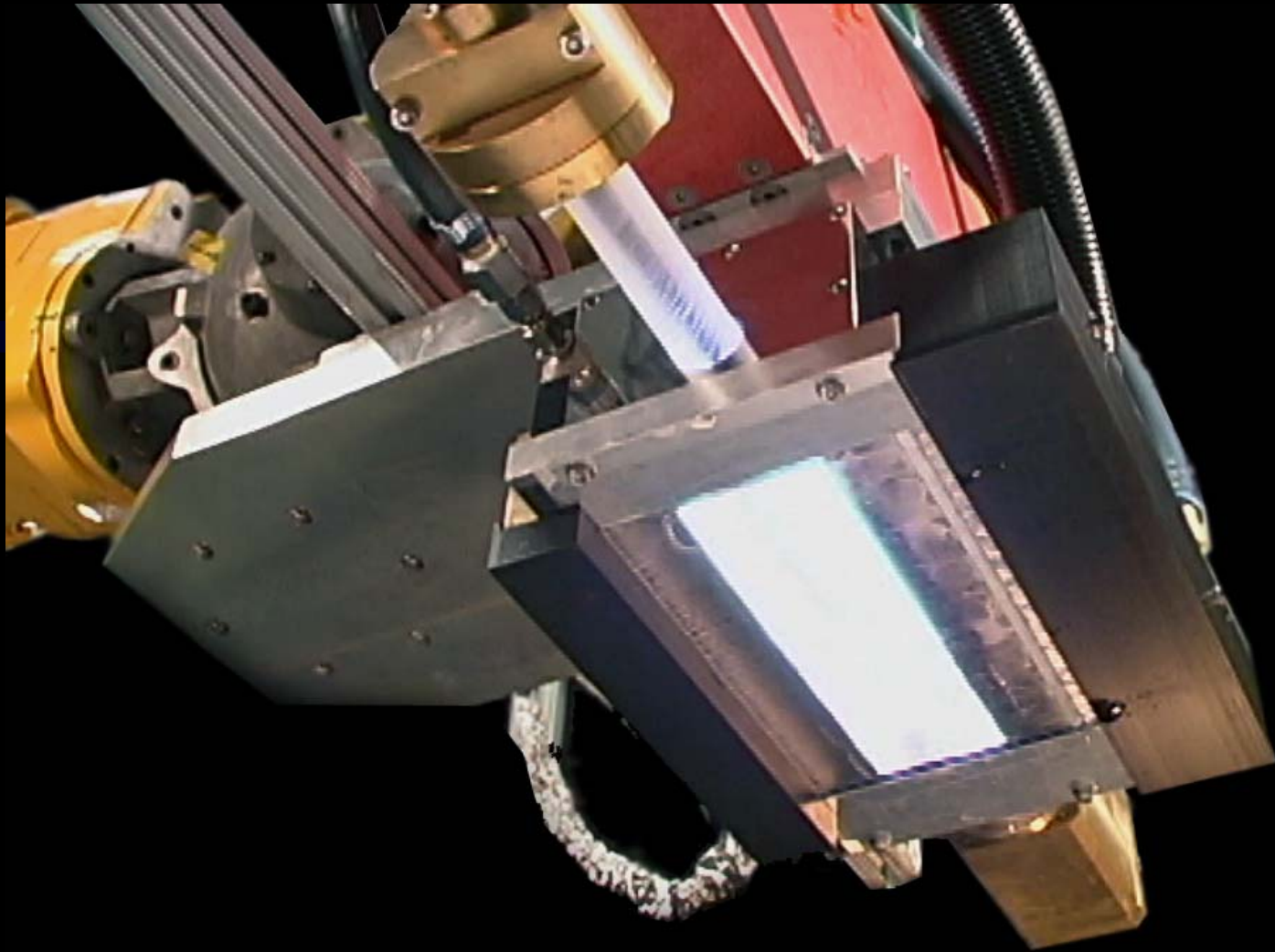
- Single source is 300,000 watts.
- Radiant output is short wavelength, 0.2 – 1.4 microns.
- Wavelength constant and independent of power level and anode/cathode wear.
- Lamp can run from 2% to 100% of available radiant output.
- Able to change power levels in less than 20 milliseconds.
- Conversion of electrical into radiant energy in excess of 55% efficient.
- Power can be delivered in a scan mode as wide as 35 cm, presently.
- Ability to tailor reflector design to specific processing needs.
- Three separate plasma heads are available at ORNL, 10, 20 and 35 cm arcs.

# *MANIPULATION OF THE PLASMA ARC LAMP*





# *WATER WINDOW TECHNOLOGY FOR LAMP SURVIVABILITY*



# *SUMMARY*



- A new high density infrared processing facility has been installed at ORNL
- The facility is state of the art and fully instrumented
- This is the most powerful Lamp in the world and has been designed for materials processing research.
- ORNL is looking for new applications

# *FOR MORE INFORMATION*



- “Aluminum Soldering, A New Look”  
IBSC 2003 Conference CD
- “High Density Infrared Processing:  
Opportunities in Aluminum,”  
by Dr. Craig A. Blue - The Aluminum  
Association, Inc. [www.aluminum.org](http://www.aluminum.org)